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ABSTRACT

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3 A power monitoring arrangement for semiconductor light
4 emitting devices used in optoelectronic packages includes a
5 mounting structure, a light emitting device, and a monitor
6 photodetector. The mounting structure has a mounting surface
7 with the light emitting device and the monitor photodetector
8 positioned thereon. The light emitting device provides emitted
9 light at a monitoring output and an active output. The monitor
10 photodetector has a light sensitive region and is positioned on
11 the mounting surface of the mounting structure proximate the
12 monitoring output of the light emitting device. A hemisphere
13 of material is formed to include at least the light sensitive
14 region of the monitor photodetector and the monitoring output
15 of the light emitting device. An outer surface of the
16 hemisphere operates as a reflecting surface to reflect light
17 from the monitoring output of the light emitting device to the
18 light sensitive region of the monitor photodetector.